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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	8051
Core Size	8-Bit
Speed	48MHz
Connectivity	CANbus, EBI/EMI, I²C, LINbus, SPI, UART/USART
Peripherals	CapSense, DMA, POR, PWM, WDT
Number of I/O	25
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 5.5V
Data Converters	A/D 16x20b; D/A 4x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	48-BSSOP (0.295", 7.50mm Width)
Supplier Device Package	48-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c3846pve-174

1. Architectural Overview

Introducing the CY8C38 family of ultra low-power, flash Programmable System-on-Chip (PSoC®) devices, part of a scalable 8-bit PSoC 3 and 32-bit PSoC 5 platform. The CY8C38 family provides configurable blocks of analog, digital, and interconnect circuitry around a CPU subsystem. The combination of a CPU with a flexible analog subsystem, digital subsystem, routing, and I/O enables a high level of integration in a wide variety of automotive consumer, industrial, and medical applications.

Figure 1-1. Simplified Block Diagram

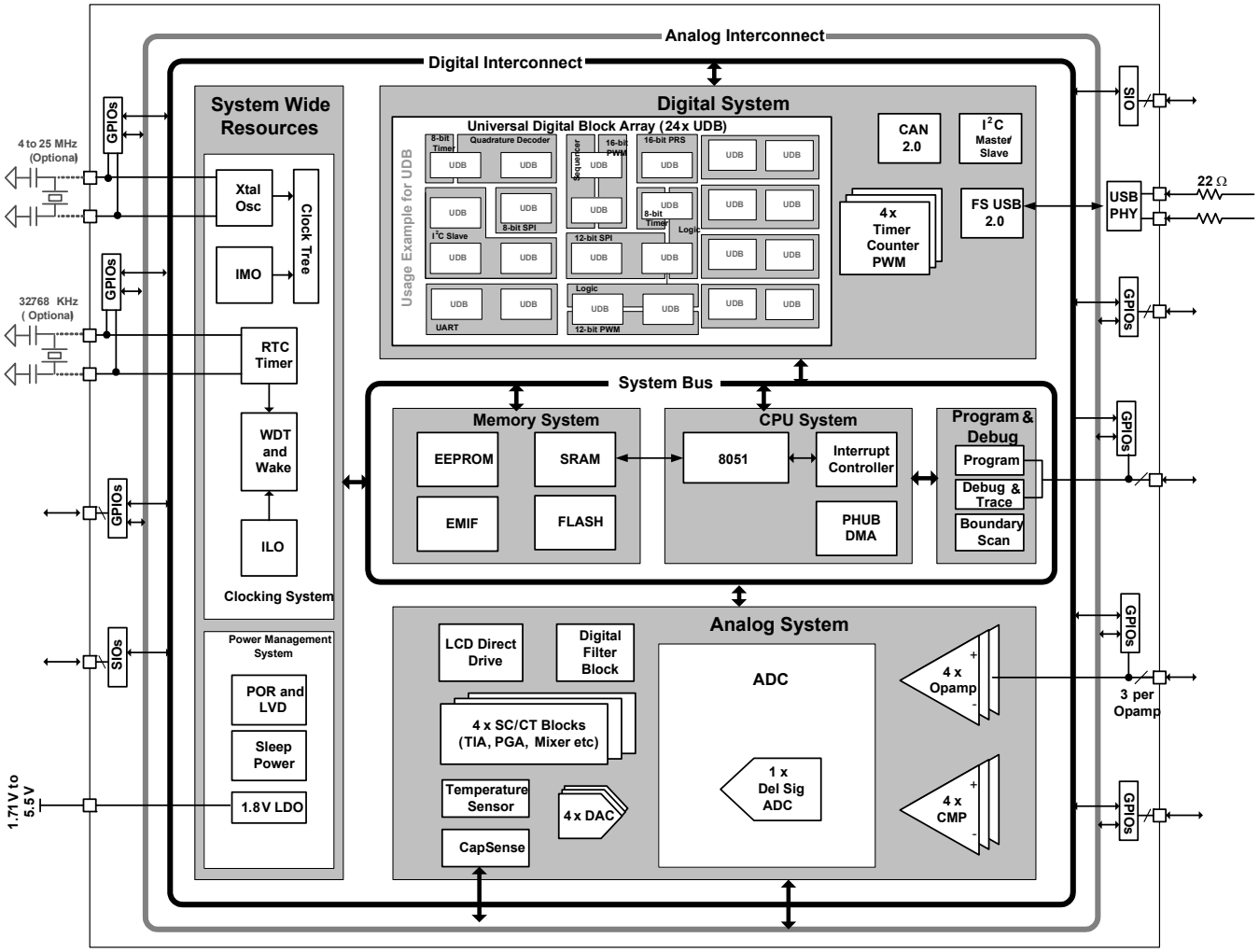


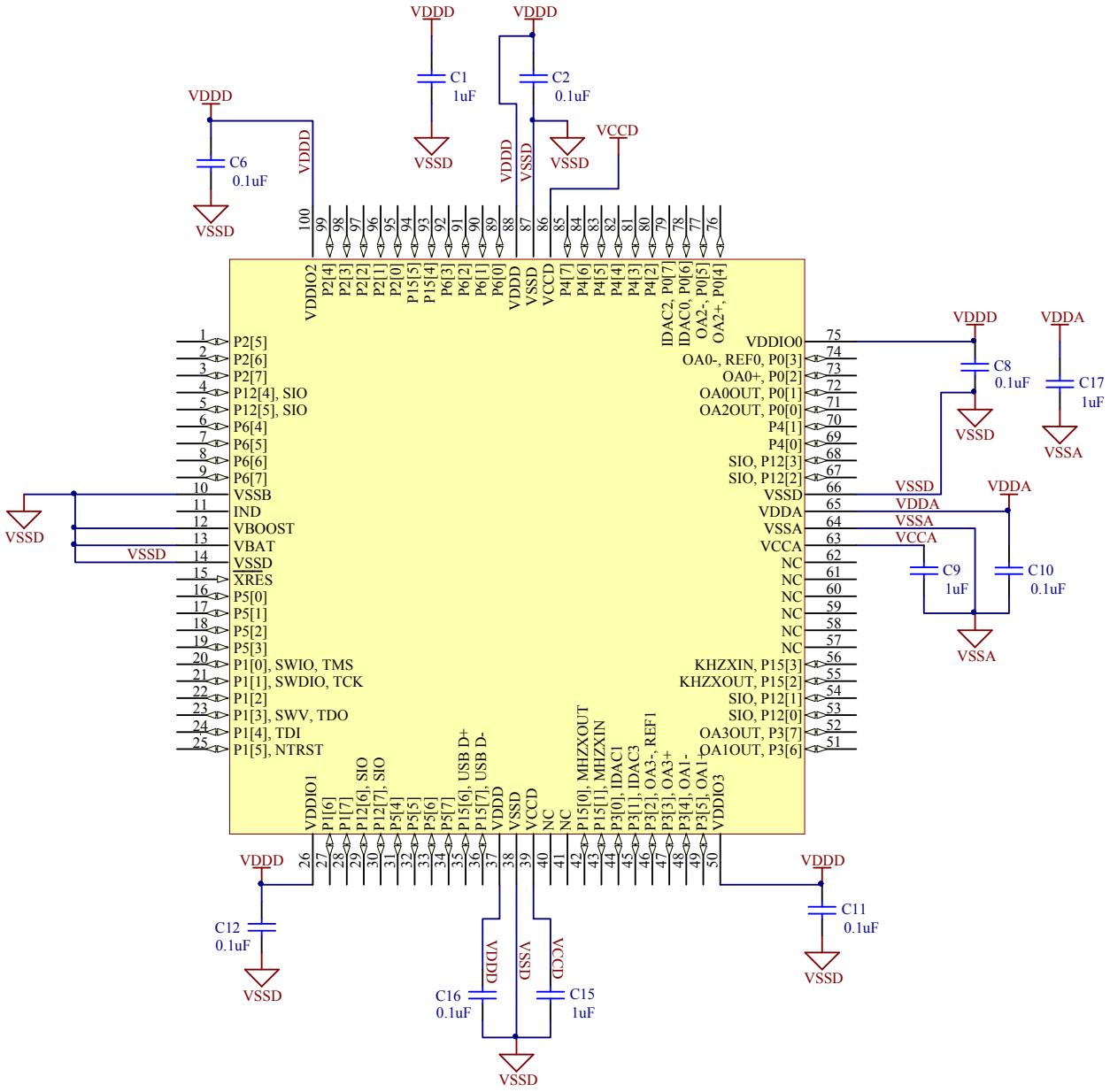
Figure 1-1 illustrates the major components of the CY8C38 family. They are:

- 8051 CPU subsystem
- Nonvolatile subsystem
- Programming, debug, and test subsystem
- Inputs and outputs
- Clocking
- Power
- Digital subsystem
- Analog subsystem

PSoC's digital subsystem provides half of its unique configurability. It connects a digital signal from any peripheral to any pin through the digital system interconnect (DSI). It also provides functional flexibility through an array of small, fast, low-power UDBs. PSoC Creator provides a library of prebuilt and tested standard digital peripherals (UART, SPI, LIN, PRS, CRC, timer, counter, PWM, AND, OR, and so on) that are mapped to the UDB array. You can also easily create a digital circuit using boolean primitives by means of graphical design entry. Each UDB contains programmable array logic (PAL)/programmable logic device (PLD) functionality, together with a small state machine engine to support a wide variety of peripherals.

In addition to the flexibility of the UDB array, PSoC also provides configurable digital blocks targeted at specific functions. For the CY8C38 family these blocks can include four 16-bit timers, counters, and PWM blocks; I²C slave, master, and multimaster; FS USB; and Full CAN 2.0b.

Figure 2-5. Example Schematic for 100-pin TQFP Part with Power Connections



Note The two Vccd pins must be connected together with as short a trace as possible. A trace under the device is recommended, as shown in Figure 2-6 on page 9.

4.4.2 DMA Features

- 24 DMA channels
- Each channel has one or more transaction descriptors (TD) to configure channel behavior. Up to 128 total TDs can be defined
- TDs can be dynamically updated
- Eight levels of priority per channel
- Any digitally routable signal, the CPU, or another DMA channel, can trigger a transaction
- Each channel can generate up to two interrupts per transfer
- Transactions can be stalled or canceled
- Supports transaction size of infinite or 1 to 64 KB
- TDs may be nested and/or chained for complex transactions

4.4.3 Priority Levels

The CPU always has higher priority than the DMA controller when their accesses require the same bus resources. Due to the system architecture, the CPU can never starve the DMA. DMA channels of higher priority (lower priority number) may interrupt current DMA transfers. In the case of an interrupt, the current transfer is allowed to complete its current transaction. To ensure latency limits when multiple DMA accesses are requested simultaneously, a fairness algorithm guarantees an interleaved minimum percentage of bus bandwidth for priority levels 2 through 7. Priority levels 0 and 1 do not take part in the fairness algorithm and may use 100 percent of the bus bandwidth. If a tie occurs on two DMA requests of the same priority level, a simple round robin method is used to evenly share the allocated bandwidth. The round robin allocation can be disabled for each DMA channel, allowing it to always be at the head of the line.

Priority levels 2 to 7 are guaranteed the minimum bus bandwidth shown in Table 4-7 after the CPU and DMA priority levels 0 and 1 have satisfied their requirements.

Table 4-7. Priority Levels

Priority Level	% Bus Bandwidth
0	100.0
1	100.0
2	50.0
3	25.0
4	12.5
5	6.2
6	3.1
7	1.5

When the fairness algorithm is disabled, DMA access is granted based solely on the priority level; no bus bandwidth guarantees are made.

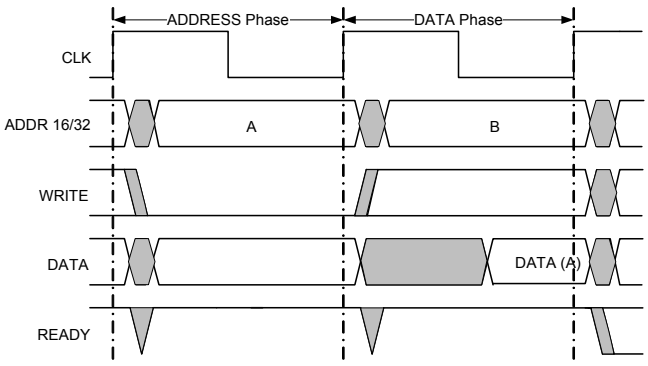
4.4.4 Transaction Modes Supported

The flexible configuration of each DMA channel and the ability to chain multiple channels allow the creation of both simple and complex use cases. General use cases include, but are not limited to:

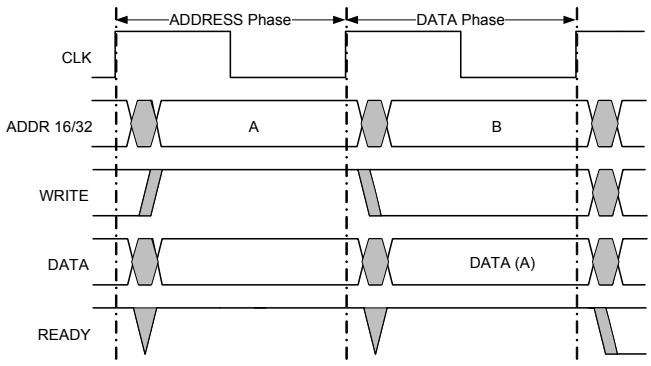
4.4.4.1 Simple DMA

In a simple DMA case, a single TD transfers data between a source and sink (peripherals or memory location). The basic timing diagrams of DMA read and write cycles are shown in Figure 4-1. For more description on other transfer modes, refer to the Technical Reference Manual.

Figure 4-1. DMA Timing Diagram



Basic DMA Read Transfer without wait states



Basic DMA Write Transfer without wait states

6.2.1 Power Modes

PSoC 3 devices have four different power modes, as shown in Table 6-2 and Table 6-3. The power modes allow a design to easily provide required functionality and processing power while simultaneously minimizing power consumption and maximizing battery life in low-power and portable devices.

PSoC 3 power modes, in order of decreasing power consumption are:

- Active
- Alternate Active
- Sleep
- Hibernate

Active is the main processing mode. Its functionality is configurable. Each power controllable subsystem is enabled or disabled by using separate power configuration template registers. In alternate active mode, fewer subsystems are enabled, reducing power. In sleep mode most resources are disabled regardless of the template settings. Sleep mode is optimized to provide timed sleep intervals and Real Time Clock functionality. The lowest power mode is hibernate, which retains register and SRAM state, but no clocks, and allows wakeup only from I/O pins. Figure 6-5 on page 31 illustrates the allowable transitions between power modes. Sleep and hibernate modes should not be entered until all VDDIO supplies are at valid voltage levels.

Table 6-2. Power Modes

Power Modes	Description	Entry Condition	Wakeup Source	Active Clocks	Regulator
Active	Primary mode of operation, all peripherals available (programmable)	Wakeup, reset, manual register entry	Any interrupt	Any (programmable)	All regulators available. Digital and analog regulators can be disabled if external regulation used.
Alternate Active	Similar to Active mode, and is typically configured to have fewer peripherals active to reduce power. One possible configuration is to use the UDBs for processing, with the CPU turned off	Manual register entry	Any interrupt	Any (programmable)	All regulators available. Digital and analog regulators can be disabled if external regulation used.
Sleep	All subsystems automatically disabled	Manual register entry	Comparator, PICU, I^2C, RTC, CTW, LVD	ILO/kHzECO	Both digital and analog regulators buzzed. Digital and analog regulators can be disabled if external regulation used.
Hibernate	All subsystems automatically disabled Lowest power consuming mode with all peripherals and internal regulators disabled, except hibernate regulator is enabled Configuration and memory contents retained	Manual register entry	PICU		Only hibernate regulator active.

Table 6-3. Power Modes Wakeup Time and Power Consumption

Sleep Modes	Wakeup Time	Current (typ)	Code Execution	Digital Resources	Analog Resources	Clock Sources Available	Wakeup Sources	Reset Sources
Active	–	1.2 mA[12]	Yes	All	All	All	–	All
Alternate Active	–	–	User defined	All	All	All	–	All
Sleep	<15 µs	1 µA	No	I^2C	Comparator	ILO/kHzECO	Comparator, PICU, I^2C, RTC, CTW, LVD	XRES, LVD, WDR
Hibernate	<100 µs	200 nA	No	None	None	None	PICU	XRES

Note
12. Bus clock off. Execute from cache at 6 MHz. See Table 11-2 on page 66.

6.4.5 Pin Interrupts

All GPIO and SIO pins are able to generate interrupts to the system. All eight pins in each port interface to their own Port Interrupt Control Unit (PICU) and associated interrupt vector. Each pin of the port is independently configurable to detect rising edge, falling edge, both edge interrupts, or to not generate an interrupt.

Depending on the configured mode for each pin, each time an interrupt event occurs on a pin, its corresponding status bit of the interrupt status register is set to '1' and an interrupt request is sent to the interrupt controller. Each PICU has its own interrupt vector in the interrupt controller and the pin status register providing easy determination of the interrupt source down to the pin level.

Port pin interrupts remain active in all sleep modes allowing the PSoC device to wake from an externally generated interrupt. While level sensitive interrupts are not directly supported; UDB provide this functionality to the system when needed.

6.4.6 Input Buffer Mode

GPIO and SIO input buffers can be configured at the port level for the default CMOS input thresholds or the optional LVTTL input thresholds. All input buffers incorporate Schmitt triggers for input hysteresis. Additionally, individual pin input buffers can be disabled in any drive mode.

6.4.7 I/O Power Supplies

Up to four I/O pin power supplies are provided depending on the device and package. Each I/O supply must be less than or equal to the voltage on the chip's analog (VDDA) pin. This feature allows users to provide different I/O voltage levels for different pins on the device. Refer to the specific device package pinout to determine VDDIO capability for a given port and pin. The SIO port pins support an additional regulated high output capability, as described in Adjustable Output Level.

6.4.8 Analog Connections

These connections apply only to GPIO pins. All GPIO pins may be used as analog inputs or outputs. The analog voltage present on the pin must not exceed the VDDIO supply voltage to which the GPIO belongs. Each GPIO may connect to one of the analog global busses or to one of the analog mux buses to connect any pin to any internal analog resource such as ADC or comparators. In addition, select pins provide direct connections to specific analog features such as the high current DACs or uncommitted opamps.

6.4.9 CapSense

This section applies only to GPIO pins. All GPIO pins may be used to create CapSense buttons and sliders[15]. See the "CapSense" section on page 58 for more information.

6.4.10 LCD Segment Drive

This section applies only to GPIO pins. All GPIO pins may be used to generate Segment and Common drive signals for direct glass drive of LCD glass. See the "LCD Direct Drive" section on page 57 for details.

6.4.11 Adjustable Output Level

This section applies only to SIO pins. SIO port pins support the ability to provide a regulated high output level for interface to external signals that are lower in voltage than the SIO's respective VDDIO. SIO pins are individually configurable to output either the standard VDDIO level or the regulated output, which is based on an internally generated reference. Typically a voltage DAC (VDAC) is used to generate the reference (see Figure 6-11). The "DAC" section on page 59 has more details on VDAC use and reference routing to the SIO pins. Resistive pullup and pull-down drive modes are not available with SIO in regulated output mode.

6.4.12 Adjustable Input Level

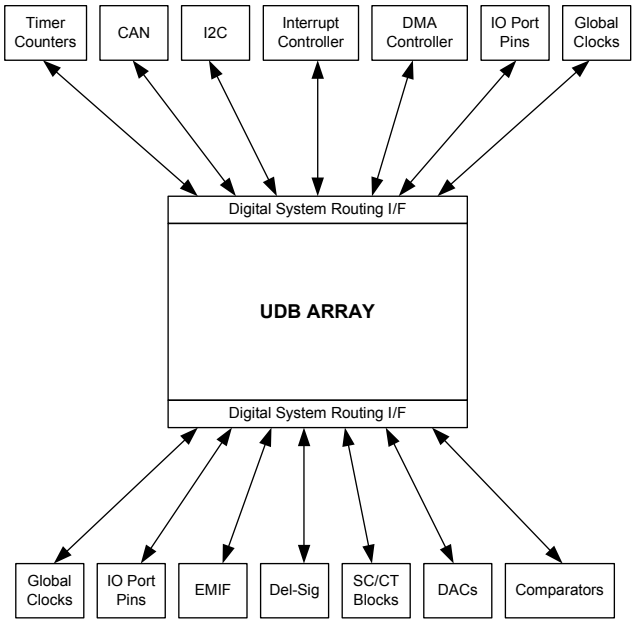
This section applies only to SIO pins. SIO pins by default support the standard CMOS and LVTTL input levels but also support a differential mode with programmable levels. SIO pins are grouped into pairs. Each pair shares a reference generator block which, is used to set the digital input buffer reference level for interface to external signals that differ in voltage from VDDIO. The reference sets the pins voltage threshold for a high logic level (see Figure 6-11). Available input thresholds are:

- 0.5 × VDDIO
- 0.4 × VDDIO
- 0.5 × V_{REF}
- V_{REF}

Typically a voltage DAC (VDAC) generates the V_{REF} reference. "DAC" section on page 59 has more details on VDAC use and reference routing to the SIO pins.

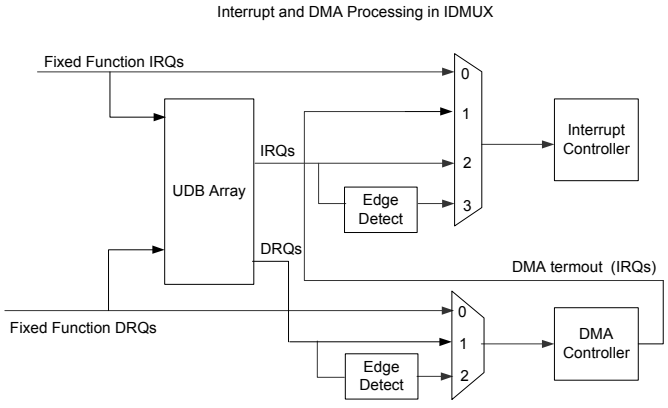
Note
15. GPIOs with opamp outputs are not recommended for use with CapSense.

Figure 7-9. Digital System Interconnect



Interrupt and DMA routing is very flexible in the CY8C38 programmable architecture. In addition to the numerous fixed function peripherals that can generate interrupt requests, any data signal in the UDB array routing can also be used to generate a request. A single peripheral may generate multiple independent interrupt requests simplifying system and firmware design. Figure 7-10 shows the structure of the IDMUX (Interrupt/DMA Multiplexer).

Figure 7-10. Interrupt and DMA Processing in the IDMUX



7.4.1 I/O Port Routing

There are a total of 20 DSI routes to a typical 8-bit I/O port, 16 for data and four for drive strength control.

When an I/O pin is connected to the routing, there are two primary connections available, an input and an output. In conjunction with drive strength control, this can implement a bidirectional I/O pin. A data output signal has the option to be single synchronized (pipelined) and a data input signal has the option to be double synchronized. The synchronization clock is the master clock (see Figure 6-1). Normally all inputs from pins are synchronized as this is required if the CPU interacts with the signal or any signal derived from it. Asynchronous inputs have rare uses. An example of this is a feed through of combinational PLD logic from input pins to output pins.

Figure 7-11. I/O Pin Synchronization Routing

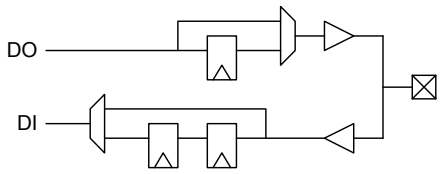
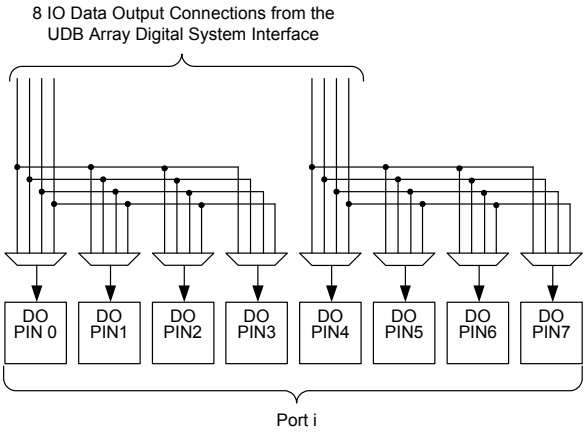
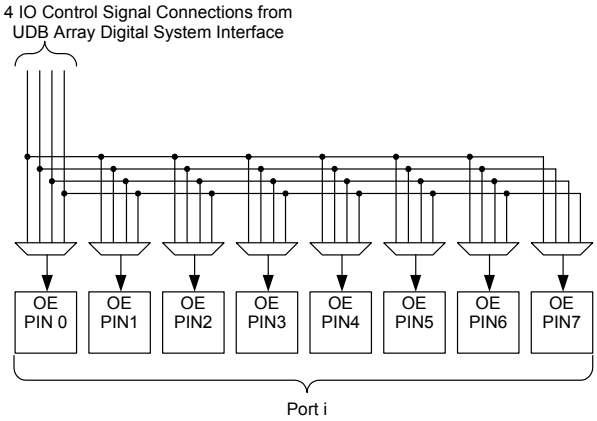


Figure 7-12. I/O Pin Output Connectivity



There are four more DSI connections to a given I/O port to implement dynamic output enable control of pins. This connectivity gives a range of options, from fully ganged 8-bits controlled by one signal, to up to four individually controlled pins. The output enable signal is useful for creating tri-state bidirectional pins and buses.

Figure 7-13. I/O Pin Output Enable Connectivity



8.2.2.3 Multi Sample

Multi sample mode is similar to continuous mode except that the ADC is reset between samples. This mode is useful when the input is switched between multiple signals. The decimator is re-primed between each sample so that previous samples do not affect the current conversion. Upon completion of a sample, the next sample is automatically initiated. The results can be transferred using either firmware polling, interrupt, or DMA.

8.2.2.4 Multi Sample (Turbo)

The multi sample (turbo) mode operates identical to the Multi-sample mode for resolutions of 8 to 16 bits. For resolutions of 17 to 20 bits, the performance is about four times faster than the multi sample mode, because the ADC is only reset once at the end of conversion.

More information on output formats is provided in the Technical Reference Manual.

8.2.3 Start of Conversion Input

The SoC signal is used to start an ADC conversion. A digital clock or UDB output can be used to drive this input. It can be used when the sampling period must be longer than the ADC conversion time or when the ADC must be synchronized to other hardware. This signal is optional and does not need to be connected if ADC is running in a continuous mode.

8.2.4 End of Conversion Output

The EoC signal goes high at the end of each ADC conversion. This signal may be used to trigger either an interrupt or DMA request.

8.3 Comparators

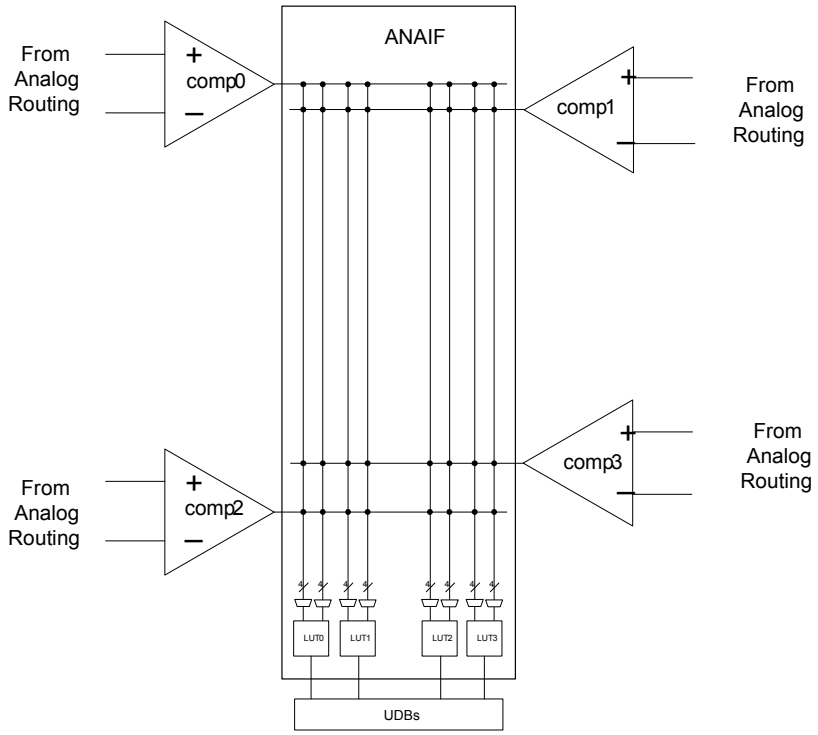
The CY8C38 family of devices contains four comparators in a device. Comparators have these features:

- Input offset factory trimmed to less than 5 mV
- Rail-to-rail common mode input range (VSSA to VDDA)
- Speed and power can be traded off by using one of three modes: fast, slow, or ultra low-power
- Comparator outputs can be routed to lookup tables to perform simple logic functions and then can also be routed to digital blocks
- The positive input of the comparators may be optionally passed through a low pass filter. Two filters are provided
- Comparator inputs can be connections to GPIO, DAC outputs and SC block outputs

8.3.1 Input and Output Interface

The positive and negative inputs to the comparators come from the analog global buses, the analog mux line, the analog local bus and precision reference through multiplexers. The output from each comparator could be routed to any of the two input LUTs. The output of that LUT is routed to the UDB DSI.

Figure 8-5. Analog Comparator



8.3.2 LUT

The CY8C38 family of devices contains four LUTs. The LUT is a two input, one output lookup table that is driven by any one or two of the comparators in the chip. The output of any LUT is routed to the digital system interface of the UDB array. From the digital system interface of the UDB array, these signals can be connected to UDBs, DMA controller, I/O, or the interrupt controller.

The LUT control word written to a register sets the logic function on the output. The available LUT functions and the associated control word is shown in Table 8-2.

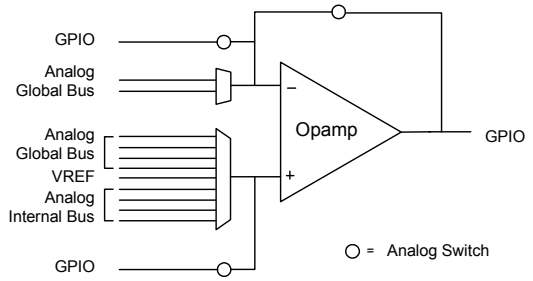
Table 8-2. LUT Function vs. Program Word and Inputs

Control Word	Output (A and B are LUT inputs)
0000b	**FALSE** (‘0’)
0001b	**A** AND **B**
0010b	**A** AND (NOT **B**)
0011b	A
0100b	(NOT **A**) AND **B**
0101b	B
0110b	**A** XOR **B**
0111b	**A** OR **B**
1000b	**A** NOR **B**
1001b	**A** XNOR **B**
1010b	NOT **B**
1011b	**A** OR (NOT **B**)
1100b	NOT **A**
1101b	(NOT **A**) OR **B**
1110b	**A** NAND **B**
1111b	**TRUE** (‘1’)

8.4 Opamps

The CY8C38 family of devices contain up to four general purpose opamps in a device.

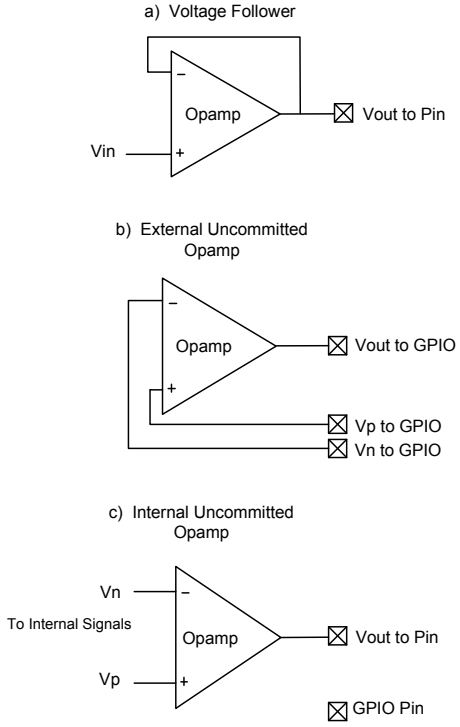
Figure 8-6. Opamp



The opamp is uncommitted and can be configured as a gain stage or voltage follower, or output buffer on external or internal signals.

See Figure 8-7. In any configuration, the input and output signals can all be connected to the internal global signals and monitored with an ADC, or comparator. The configurations are implemented with switches between the signals and GPIO pins.

Figure 8-7. Opamp Configurations



The opamp has three speed modes, slow, medium, and fast. The slow mode consumes the least amount of quiescent power and the fast mode consumes the most power. The inputs are able to swing rail-to-rail. The output swing is capable of rail-to-rail operation at low current output, within 50 mV of the rails. When driving high current loads (about 25 mA) the output voltage may only get within 500 mV of the rails.

8.5 Programmable SC/CT Blocks

The CY8C38 family of devices contains up to four switched capacitor/continuous time (SC/CT) blocks in a device. Each switched capacitor/continuous time block is built around a single rail-to-rail high bandwidth opamp.

Switched capacitor is a circuit design technique that uses capacitors plus switches instead of resistors to create analog functions. These circuits work by moving charge between capacitors by opening and closing different switches. Nonoverlapping in phase clock signals control the switches, so that not all switches are ON simultaneously.

The PSoC Creator tool offers a user friendly interface, which allows you to easily program the SC/CT blocks. Switch control and clock phase control configuration is done by PSoC Creator so users only need to determine the application use parameters such as gain, amplifier polarity, V_{REF} connection, and so on.

The same opamps and block interfaces are also connectable to an array of resistors which allows the construction of a variety of continuous time functions.

The opamp and resistor array is programmable to perform various analog functions including

- Naked operational amplifier – Continuous mode
- Unity-gain buffer – Continuous mode
- PGA – Continuous mode
- Transimpedance amplifier (TIA) – Continuous mode
- Up/down mixer – Continuous mode
- Sample and hold mixer (NRZ S/H) – Switched cap mode
- First order analog to digital modulator – Switched cap mode

8.5.1 Naked Opamp

The Naked Opamp presents both inputs and the output for connection to internal or external signals. The opamp has a unity gain bandwidth greater than 6.0 MHz and output drive current up to 650 µA. This is sufficient for buffering internal signals (such as DAC outputs) and driving external loads greater than 7.5 kohms.

8.5.2 Unity Gain

The Unity Gain buffer is a Naked Opamp with the output directly connected to the inverting input for a gain of 1.00. It has a –3 dB bandwidth greater than 6.0 MHz.

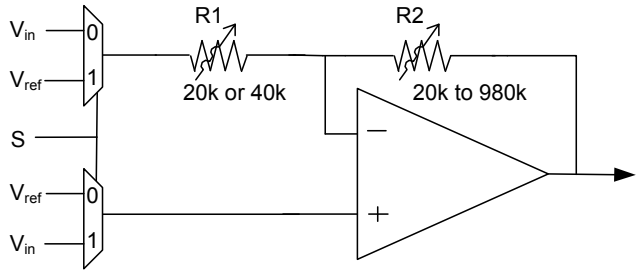
8.5.3 PGA

The PGA amplifies an external or internal signal. The PGA can be configured to operate in inverting mode or noninverting mode. The PGA function may be configured for both positive and negative gains as high as 50 and 49 respectively. The gain is adjusted by changing the values of R1 and R2 as illustrated in Figure 8-8. The schematic in Figure 8-8 shows the configuration and possible resistor settings for the PGA. The gain is switched from inverting and non inverting by changing the shared select value of the both the input muxes. The bandwidth for each gain case is listed in Table 8-3.

Table 8-3. Bandwidth

Gain	Bandwidth
1	5.5 MHz
24	340 kHz
48	220 kHz
50	215 kHz

Figure 8-8. PGA Resistor Settings



The PGA is used in applications where the input signal may not be large enough to achieve the desired resolution in the ADC, or dynamic range of another SC/CT block such as a mixer. The gain is adjustable at runtime, including changing the gain of the PGA prior to each ADC sample.

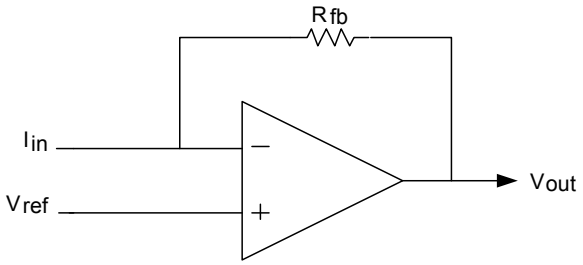
8.5.4 TIA

The Transimpedance Amplifier (TIA) converts an internal or external current to an output voltage. The TIA uses an internal feedback resistor in a continuous time configuration to convert input current to output voltage. For an input current I_{in}, the output voltage is V_{REF} - I_{in} x R_{fb}, where V_{REF} is the value placed on the non inverting input. The feedback resistor Rfb is programmable between 20 KΩ and 1 MΩ through a configuration register. Table 8-4 shows the possible values of Rfb and associated configuration settings.

Table 8-4. Feedback Resistor Settings

Configuration Word	Nominal R_{fb} (KΩ)
000b	20
001b	30
010b	40
011b	60
100b	120
101b	250
110b	500
111b	1000

Figure 8-9. Continuous Time TIA Schematic



The TIA configuration is used for applications where an external sensor's output is current as a function of some type of stimulus such as temperature, light, magnetic flux etc. In a common application, the voltage DAC output can be connected to the V_{REF} TIA input to allow calibration of the external sensor bias current by adjusting the voltage DAC output voltage.

8.6 LCD Direct Drive

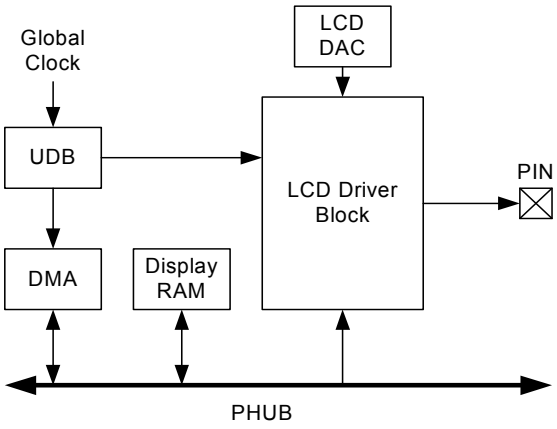
The PSoC LCD driver system is a highly configurable peripheral designed to allow PSoC to directly drive a broad range of LCD glass. All voltages are generated on chip, eliminating the need for external components. With a high multiplex ratio of up to 1/16, the CY8C38 family LCD driver system can drive a maximum of 736 segments. The PSoC LCD driver module was also designed with the conservative power budget of portable devices in mind, enabling different LCD drive modes and power down modes to conserve power.

PSoC Creator provides an LCD segment drive component. The component wizard provides easy and flexible configuration of LCD resources. You can specify pins for segments and commons along with other options. The software configures the device to meet the required specifications. This is possible because of the programmability inherent to PSoC devices.

Key features of the PSoC LCD segment system are:

- LCD panel direct driving
- Type A (standard) and Type B (low-power) waveform support
- Wide operating voltage range support (2 V to 5 V) for LCD panels
- Static, 1/2, 1/3, 1/4, 1/5 bias voltage levels
- Internal bias voltage generation through internal resistor ladder
- Up to 62 total common and segment outputs
- Up to 1/16 multiplex for a maximum of 16 backplane/common outputs
- Up to 62 front plane/segment outputs for direct drive
- Drives up to 736 total segments (16 backplane × 46 front plane)
- Up to 64 levels of software controlled contrast
- Ability to move display data from memory buffer to LCD driver through DMA (without CPU intervention)
- Adjustable LCD refresh rate from 10 Hz to 150 Hz
- Ability to invert LCD display for negative image
- Three LCD driver drive modes, allowing power optimization

Figure 8-10. LCD System



8.6.1 LCD Segment Pin Driver

Each GPIO pin contains an LCD driver circuit. The LCD driver buffers the appropriate output of the LCD DAC to directly drive the glass of the LCD. A register setting determines whether the pin is a common or segment. The pin's LCD driver then selects one of the six bias voltages to drive the I/O pin, as appropriate for the display data.

8.6.2 Display Data Flow

The LCD segment driver system reads display data and generates the proper output voltages to the LCD glass to produce the desired image. Display data resides in a memory buffer in the system SRAM. Each time you need to change the common and segment driver voltages, the next set of pixel data moves from the memory buffer into the Port Data Registers through the DMA.

8.6.3 UDB and LCD Segment Control

A UDB is configured to generate the global LCD control signals and clocking. This set of signals is routed to each LCD pin driver through a set of dedicated LCD global routing channels. In addition to generating the global LCD control signals, the UDB also produces a DMA request to initiate the transfer of the next frame of LCD data.

8.6.4 LCD DAC

The LCD DAC generates the contrast control and bias voltage for the LCD system. The LCD DAC produces up to five LCD drive voltages plus ground, based on the selected bias ratio. The bias voltages are driven out to GPIO pins on a dedicated LCD bias bus, as required.

8.7 CapSense

The CapSense system provides a versatile and efficient means for measuring capacitance in applications such as touch sense buttons, sliders, proximity detection, etc. The CapSense system uses a configuration of system resources, including a few hardware functions primarily targeted for CapSense. Specific resource usage is detailed in the CapSense component in PSoC Creator.

A capacitive sensing method using a Delta-sigma Modulator (CSD) is used. It provides capacitance sensing using a switched capacitor technique with a delta-sigma modulator to convert the sensing current to a digital code.

8.8 Temp Sensor

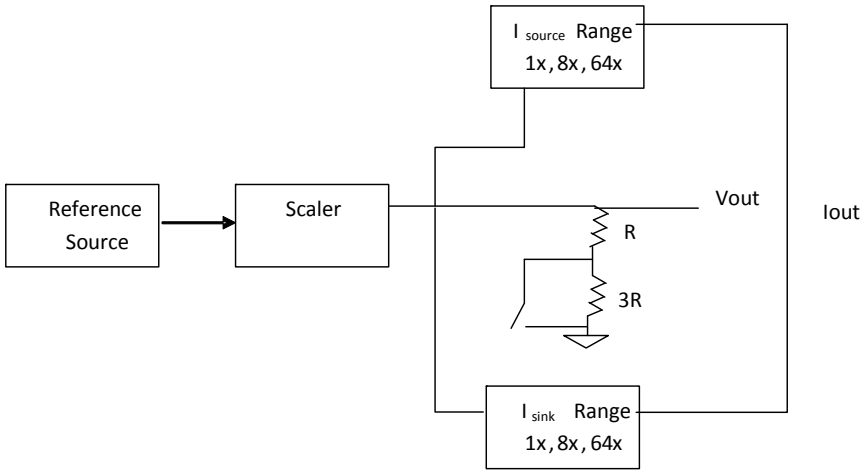
Die temperature is used to establish programming parameters for writing flash. Die temperature is measured using a dedicated sensor based on a forward biased transistor. The temperature sensor has its own auxiliary ADC.

8.9 DAC

The CY8C38 parts contain up to four Digital to Analog Convertors (DACs). Each DAC is 8-bit and can be configured for either voltage or current output. The DACs support CapSense, power supply regulation, and waveform generation. Each DAC has the following features:

- Adjustable voltage or current output in 255 steps
- Programmable step size (range selection)
- Eight bits of calibration to correct ± 25 percent of gain error
- Source and sink option for current output
- High and low speed / power modes
- 8 Msps conversion rate for current output
- 1 Msps conversion rate for voltage output
- Monotonic in nature
- Data and strobe inputs can be provided by the CPU or DMA, or routed directly from the DSI
- Dedicated low-resistance output pin for high-current mode

Figure 8-11. DAC Block Diagram



8.9.1 Current DAC

The current DAC (IDAC) can be configured for the ranges 0 to 31.875 µA, 0 to 255 µA, and 0 to 2.04 mA. The IDAC can be configured to source or sink current.

8.9.2 Voltage DAC

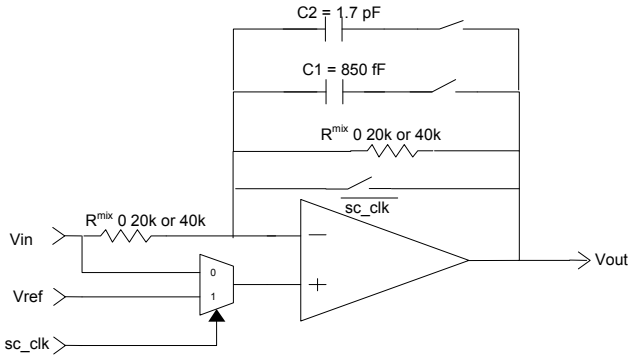
For the voltage DAC (VDAC), the current DAC output is routed through resistors. The two ranges available for the VDAC are 0 to 1.02 V and 0 to 4.08 V. In voltage mode any load connected to the output of a DAC should be purely capacitive (the output of the VDAC is not buffered).

8.10 Up/Down Mixer

In continuous time mode, the SC/CT block components are used to build an up or down mixer. Any mixing application contains an input signal frequency and a local oscillator frequency. The polarity of the clock, Fclk, switches the amplifier between inverting or noninverting gain. The output is the product of the input and the switching function from the local oscillator, with frequency components at the local oscillator plus and minus the signal frequency (Fclk + Fin and Fclk – Fin) and reduced-level frequency components at odd integer multiples of the local oscillator frequency. The local oscillator frequency is provided by the selected clock source for the mixer.

Continuous time up and down mixing works for applications with input signals and local oscillator frequencies up to 1 MHz.

Figure 8-12. Mixer Configuration



8.11 Sample and Hold

The main application for a sample and hold, is to hold a value stable while an ADC is performing a conversion. Some applications require multiple signals to be sampled simultaneously, such as for power calculations (V and I).

Table 11-2. DC Specifications *(continued)*

Parameter	Description	Conditions	Min	Typ	Max	Units
Idd[24, 25]	**Active Mode, VDD = 1.71 V - 5.5 V**					
	Execute from CPU instruction buffer, see Flash Program Memory on page 21					
	CPU at 3 MHz	T = –40 °C	–	1.3	2.9	mA
		T = 25 °C	–	1.6	3.2	mA
		T = 85 °C	–	4.8	7.5	mA
		T = 125 °C	–	4.9	7.7	mA
	CPU at 6 MHz	T = –40 °C	–	2.1	3.7	mA
		T = 25 °C	–	2.3	3.9	mA
		T = 85 °C	–	5.6	8.5	mA
		T = 125 °C	–	5.8	8.7	mA
	CPU at 12 MHz	T = –40 °C	–	3.5	5.2	mA
		T = 25 °C	–	3.8	5.5	mA
		T = 85 °C	–	7.1	9.8	mA
		T = 125 °C	–	9.0	10	mA
	CPU at 24 MHz	T = –40 °C	–	6.3	8.1	mA
		T = 25 °C	–	6.6	8.3	mA
		T = 85 °C	–	10	13	mA
		T = 125 °C	–	12	14	mA
	CPU at 48 MHz	T = –40 °C	–	11.5	13.5	mA
		T = 25 °C	–	12	14	mA
		T = 85 °C	–	15.5	18.5	mA
		T = 125 °C	–	16.5	19	mA
	CPU at 62 MHz	T = –40 °C	–	16	18	mA
		T = 25 °C	–	16	18	mA
		T = 85 °C	–	19.5	23	mA
		T = 125 °C	–	20	24	mA

Notes
24. The current consumption of additional peripherals that are implemented only in programmed logic blocks can be found in their respective data sheets, available in PSoC Creator, the integrated design environment. To compute total current, find CPU current at frequency of interest and add peripheral currents for your particular system from the device data sheet and component data sheets.
25. Total current for all power domains: digital (I_{DDD}), analog (I_{DDA}), and I/Os ($I_{DDIO0, 1, 2, 3}$). All I/Os floating.

Table 11-7. GPIO AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
TriseF	Rise time in Fast Strong Mode[30]	3 V Vddio Cload = 25 pF	–	–	12	ns
TfallF	Fall time in Fast Strong Mode[30]	3 V Vddio Cload = 25 pF	–	–	12	ns
TriseS	Rise time in Slow Strong Mode[30]	3 V Vddio Cload = 25 pF	–	–	60	ns
TfallS	Fall time in Slow Strong Mode[30]	3 V Vddio Cload = 25 pF	–	–	60	ns
Fgpioout	GPIO output operating frequency					
	3 V ≤ Vddio ≤ 5.5 V, fast strong drive mode	90/10% Vddio into 25 pF, -40°C ≤ Ta ≤ 85°C and Tj ≤ 100°C	-	-	33	MHz
		90/10% Vddio into 25 pF, -40°C ≤ Ta ≤ 125°C and Tj ≤ 150°C	-	-	24	MHz
	1.71 V ≤ Vddio < 3 V, fast strong drive mode	90/10% Vddio into 25 pF, -40°C ≤ Ta ≤ 85°C and Tj ≤ 100°C	-	-	20	MHz
		90/10% Vddio into 25 pF, -40°C ≤ Ta ≤ 125°C and Tj ≤ 150°C	-	-	16	MHz
	3 V ≤ Vddio ≤ 5.5 V, slow strong drive mode	90/10% Vddio into 25 pF, -40°C ≤ Ta ≤ 85°C and Tj ≤ 100°C	-	-	7	MHz
		90/10% Vddio into 25 pF, -40°C ≤ Ta ≤ 125°C and Tj ≤ 150°C	-	-	7	MHz
	1.71 V ≤ Vddio < 3 V, slow strong drive mode	90/10% Vddio into 25 pF, -40°C ≤ Ta ≤ 85°C and Tj ≤ 100°C	-	-	3.5	MHz
		90/10% Vddio into 25 pF, -40°C ≤ Ta ≤ 125°C and Tj ≤ 150°C	-	-	3.5	MHz
Fgpioin	GPIO input operating frequency					
	1.71 V ≤ Vddio ≤ 5.5 V	90/10% better than 60/40 duty cycle, -40°C ≤ Ta ≤ 85°C and Tj ≤ 100°C	-	-	66	MHz
		90/10% better than 60/40 duty cycle, -40°C ≤ Ta ≤ 125°C and Tj ≤ 150°C	-	-	50	MHz

Figure 11-17. Opamp Voffset vs Temperature, Vdda = 5 V

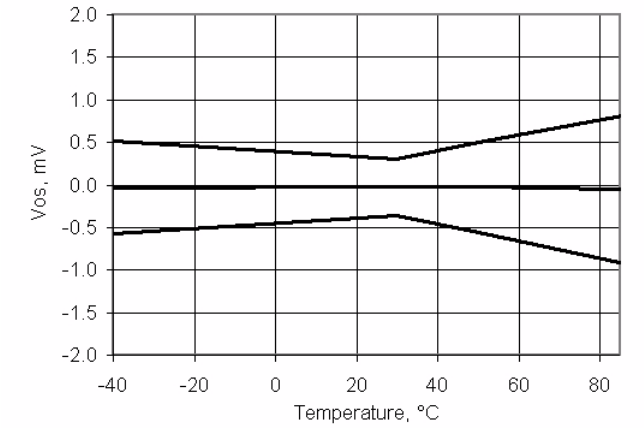


Figure 11-18. Opamp Voffset vs Vcommon and Vdda, 25 °C

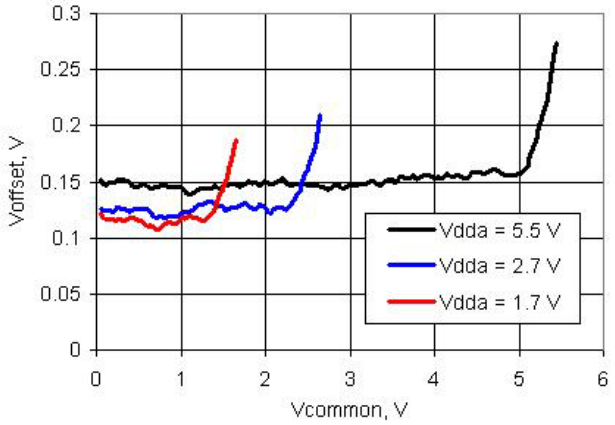
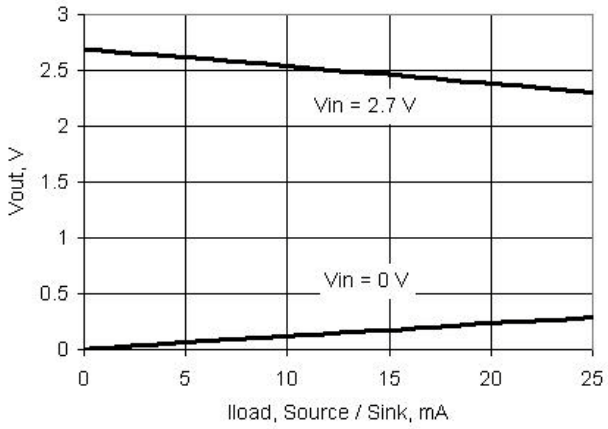


Figure 11-19. Opamp Output Voltage vs Load Current and Temperature, High Power Mode, 25 °C, Vdda = 2.7 V



11.5.3 Voltage Reference

Table 11-24. Voltage Reference Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
Vref [39]	Precision reference	-40°C ≤ Ta ≤ 85°C and Tj ≤ 100°C	1.021 (-0.3%)	1.024	1.027 (+0.3%)	V
		-40°C ≤ Ta ≤ 125°C and Tj ≤ 150°C	1.018 (–0.6%)	1.024	1.030 (+0.6%)	V
	After typical PCB assembly, post reflow	Typical (non-optimized) board layout and 250 °C solder reflow. Device may be calibrated after assembly to improve performance.				
		–40 °C		±0.5		%
		25 °C		±0.2		%
		85 °C		±0.2		%
	Temperature drift[40]	Box method	–	–	30	ppm/°C
	Long term drift		–	100	–	ppm/khr
	Thermal cycling drift (stability)[40, 41]		–	100	–	ppm

Figure 11-30. Voltage Reference vs. Temperature and V_{CCA}

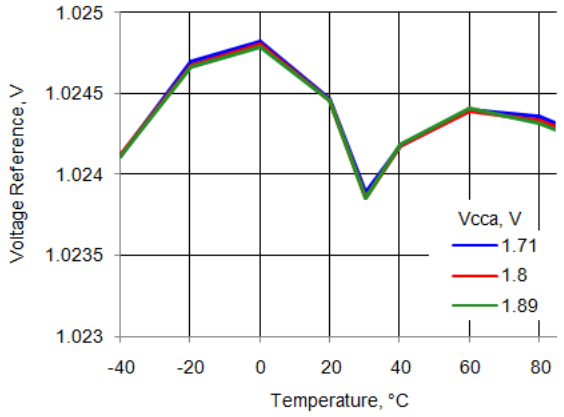
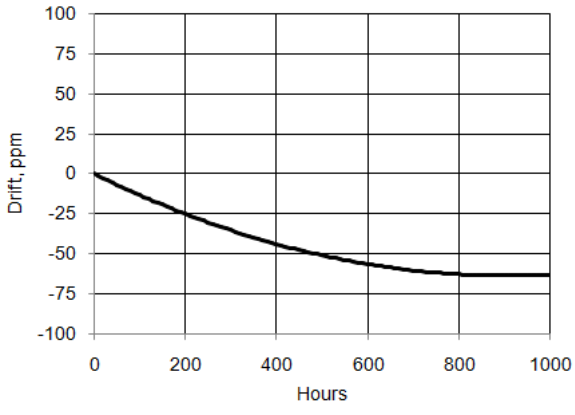


Figure 11-31. Voltage Reference Long-Term Drift



Notes
39. V_{REF} is measured after packaging, and thus accounts for substrate and die attach stresses.
40. Based on device characterization (Not production tested).
41. After eight full cycles between –40 °C and 100 °C.

Table 11-29. IDAC (Current Digital-to-Analog Converter) AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
Fdac	Update rate		–	–	8	Msps
T_{SETTLE}	Settling time to 0.5 LSB	Range = 31.875 µA or 255 µA, full scale transition, High speed mode, 600 Ω 15-pF load	–	–	125	ns
	Current noise	Range = 255 µA, source mode, High speed mode, Vdda = 5 V, 10 kHz	–	340	–	pA/sqrtHz

Figure 11-42. IDAC Step Response, Codes 0x40 - 0xC0, 255 µA Mode, Source Mode, High speed mode, Vdda = 5 V

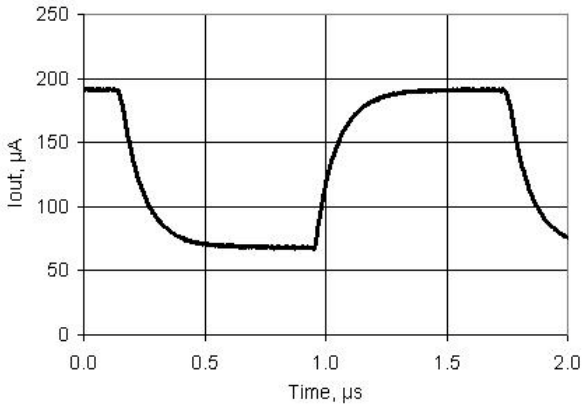
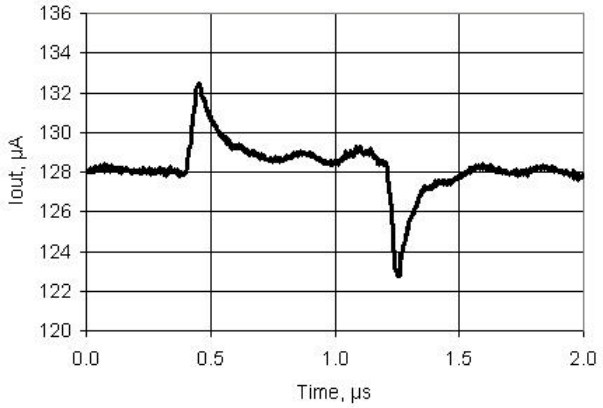


Figure 11-43. IDAC Glitch Response, Codes 0x7F - 0x80, 255 µA Mode, Source Mode, High speed mode, Vdda = 5 V

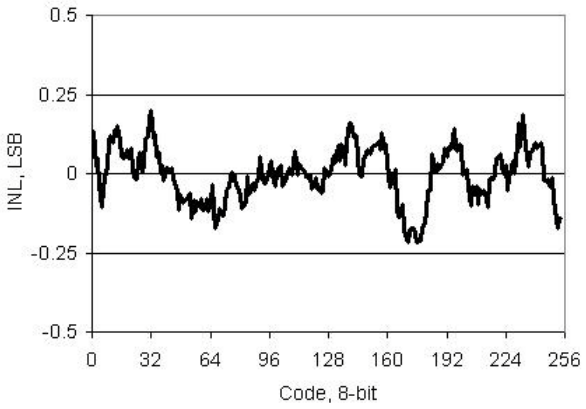


11.5.7 VDAC

Table 11-30. VDAC (Voltage Digital-to-Analog Converter) DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
Resolution			-	8	-	
Rout	Output resistance[30]					
	High	Vout = 4 V	-	16	-	kΩ
	Low	Vout = 1 V	-	4	-	kΩ
Vout	Output voltage range, code = 255	1 V scale	–	1.02	–	V
		4 V scale, Vdda = 5 V	–	4.08	–	V
INL	Integral nonlinearity	1 V scale	–	±2.1	±2.5	LSB
DNL	Differential nonlinearity	1 V scale	–	±0.3	±1	LSB
	Monotonicity		–	–	Yes	–
Eg	Gain error	1 V scale,	–	–	±2.5	%
		4 V scale	–	–	±2.5	%
TC_Eg	Temperature coefficient, gain error	1 V scale,	–	–	0.03	%FSR / °C
		4 V scale	–	–	0.03	%FSR / °C
VDAC_ICC	Operating current	Low speed mode	–	–	100	µA
		High speed mode	–	–	500	µA
V_{OS}	Zero scale error		–	0	±0.9	LSB

Figure 11-46. VDAC INL vs Input Code, 1 V Mode



11.5.12 LCD Direct Drive

Table 11-39. LCD Direct Drive DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
I_{CC}	LCD system operating current	Device sleep mode with wakeup at 400-Hz rate to refresh LCDs, bus clock = 3 Mhz, Vddio = Vdda = 3 V, 4 commons, 16 segments, 1/4 duty cycle, 50 Hz frame rate, no glass connected	–	38	–	µA
I_{CC_SEG}	Current per segment driver	Strong drive mode	–	260	–	µA
V_{BIAS}	LCD bias range (V_{BIAS} refers to the main output voltage(V0) of LCD DAC)	$V_{DDA} \geq 3$ V and $V_{DDA} \geq V_{BIAS}$	2	–	5	V
	LCD bias step size	$V_{DDA} \geq 3$ V and $V_{DDA} \geq V_{BIAS}$	–	9.1 × V_{DDA}	–	mV
	LCD capacitance per segment/common driver	Drivers may be combined	–	500	5000	pF
	Long term segment offset		–	–	20	mV
I_{OUT}	Output drive current per segment driver)	Vddio = 5.5V, strong drive mode	355	–	710	µA

Table 11-40. LCD Direct Drive AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
f_{LCD}	LCD frame rate		10	50	150	Hz

Figure 11-62. Asynchronous Write Cycle Timing

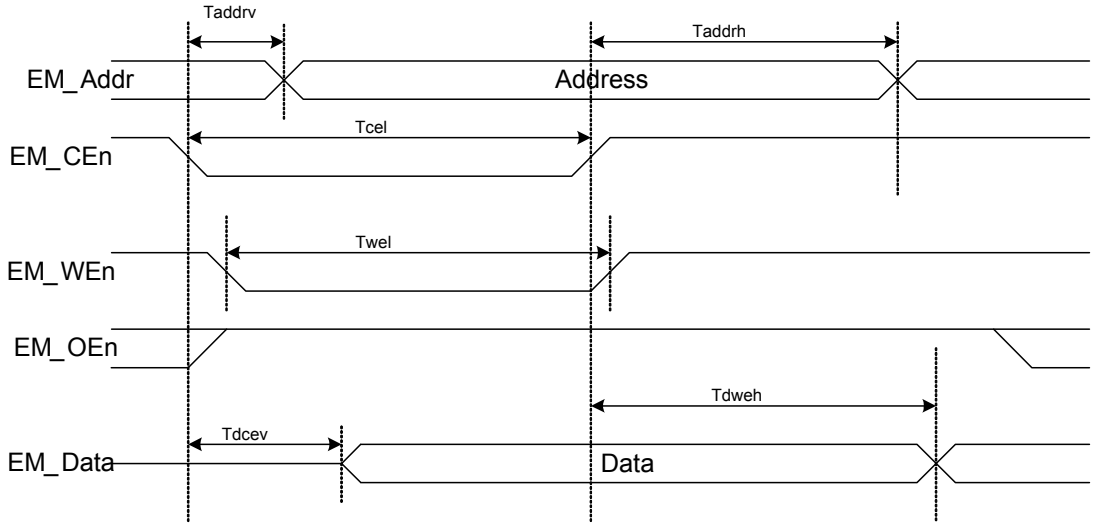
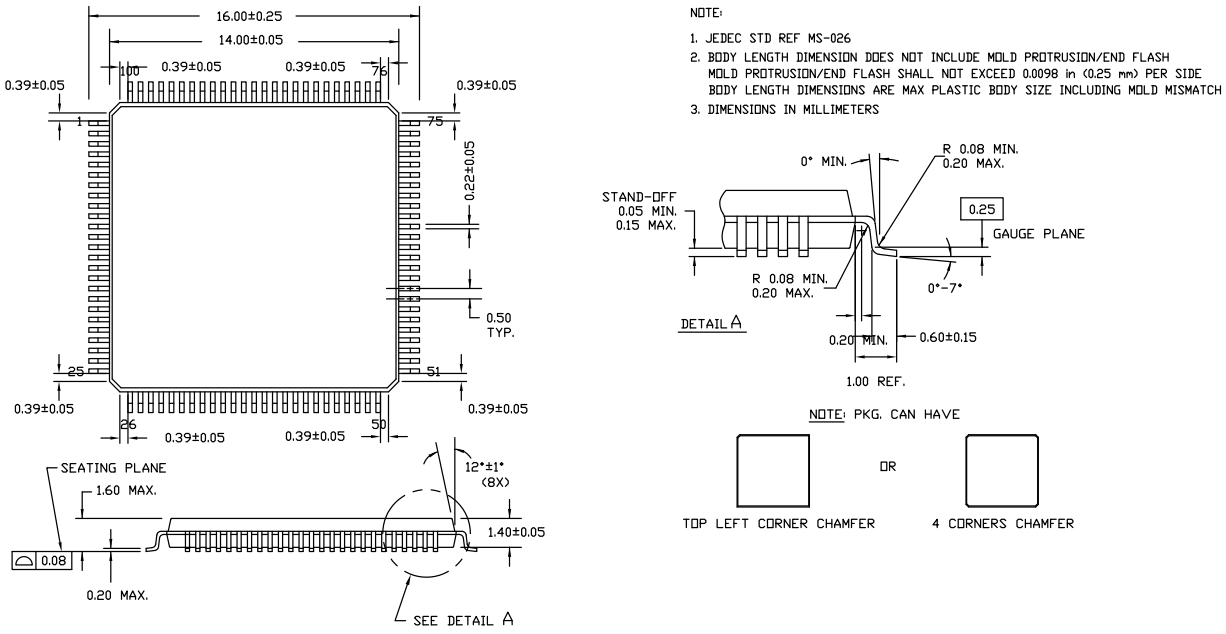


Table 11-64. Asynchronous Write Cycle Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
T	EMIF clock period[56]	Vdda ≥ 3.3 V	30.3	–	–	ns
Tcel	EM_CEn low time		T – 5	–	T + 5	ns
Taddrv	EM_CEn low to EM_Addr valid		–	–	5	ns
Taddrh	Address hold time after EM_WEn high		T	–	–	ns
Twel	EM_WEn low time		T – 5	–	T + 5	ns
Tdcev	EM_CEn low to data valid		–	–	7	ns
Tdweh	Data hold time after EM_WEn high		T	–	–	ns

Figure 13-2. 100-pin TQFP (14 × 14 × 1.4 mm) A100SA Package Outline, 51-85048



51-85048 *I